

3. Specifications are subject to change without notice.

SPECIFICATION CS63BDR3C

PACKAGE OUTLINES 1.60 [0.06"] RECOMMENDED PAD LAYOUT 0.80[0.03"] [0,01"] 0.80[0.03"] 1.10 [0.04"] 2.40[0.09"] 0.50 [0.02"] Notes: 1. All dimensions are in millimeters (inches). 2. Tolerance is \pm 0.25mm (0.01") unless otherwised noted.

Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CS63BDR3C	InGaAIP	Red	Water Clear	140°





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lR	10	μΑ	
Power Dissipation	Pd	75	mW	
Operating Temperature Range	Тор	-40~+80	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	125	mA	
Soldering Temperature	TsoL	Max 260°C for 10 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Darameter	Symbol	Test Condition	Value			Linit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	160	230	-	mcd
Forward Voltage	VF	IF = 20mA	1	2.0	2.5	V
Reverse Leakage Current	lR	VR = 5V	-	10	-	μΑ
Viewing Angle at 50% Iv	201/2	IF = 10mA	ı	140	-	Deg
Peak Wavelength	λР	IF = 20mA	-	655	1	nm
Dominant Wavelength	λD	IF = 20mA	630	640	650	nm

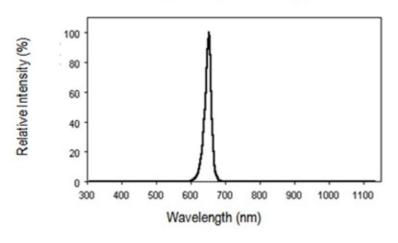
^{*}Tolerance of viewing angle: -10 / +5 deg.



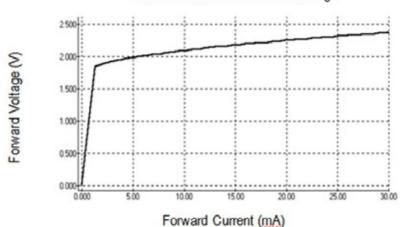


OPTICAL CHARACTERISTIC CURVES

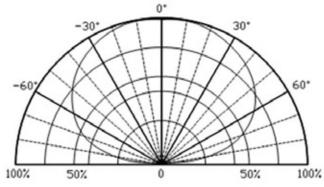
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage



Directive Characteristics

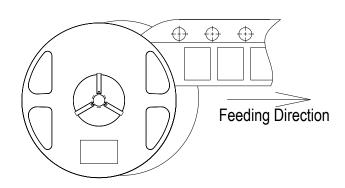


RoHS Compliant

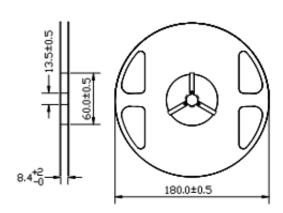


PACKAGING SPECIFICATION

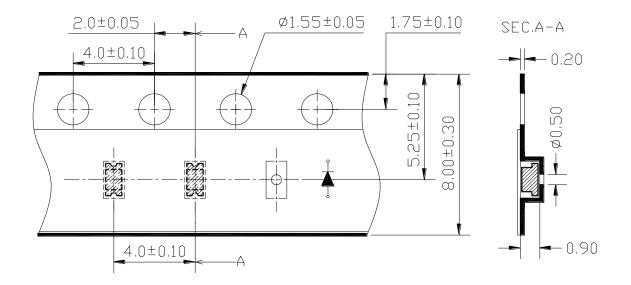
• Feeding Direction



• Dimensions of Reel (Unit: mm)



• Dimensions of Tape (Unit: mm)



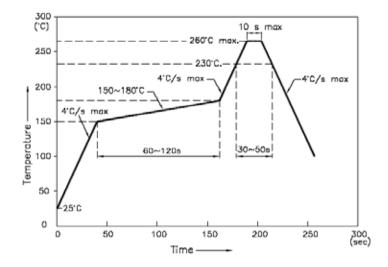
Notes:

- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The cathode is oriented towards the tape sprocket hole.
- 4. 4,000pcs/Reel





SOLDERING CONDITIONS



NOTES:

- 1. We recommend the reflow temperature 245°C (±5°C).the maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.
 - Soldering iron
 - Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter
 - (+10°C → -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron cannot touch copper foil
- 3. Twin-head type is preferred.

